

ESD9B5VL

1-Line, Bi-directional, Transient Voltage Suppressor

Descriptions

The ESD9B5VL is a bi-directional TVS (Transient Voltage Suppressor). It is specifically designed to protect sensitive electronic components which are connected to low speed data lines and control lines from over-stress caused by ESD (Electrostatic Discharge), EFT (Electrical Fast Transients) and Lightning.

The ESD9B5VL may be used to provide ESD protection up to ±20kV (contact and air discharge) according to IEC61000-4-2, and withstand peak pulse current up to 3A (8/20µs) according to IEC61000-4-5.

The ESD9B5VL is available in FBP-02C package. Standard products are Pb-free and Halogen-free.

Features

- Reverse stand-off voltage: ±5V Max
- Transient protection for each line according to IEC61000-4-2 (ESD): ±20kV (contact and air discharge) IEC61000-4-4 (EFT): 20A (5/50ns) IEC61000-4-5 (surge): 3A (8/20µs)
- Capacitance: C_J = 5.0pF typ.
- Low leakage current: I_R < 1nA typ.
- Low clamping voltage: V_{CL} = 13V typ. @ I_{PP} = 16A (TLP)
- Solid-state silicon technology

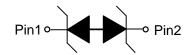
Applications

- Cellular handsets
- Tablets
- Laptops
- Other portable devices
- Network communication devices

http//:www.sh-willsemi.com



FBP-02C (Bottom View)



Circuit diagram



* = Month code (A~Z)

.B = Device Code

Marking (Top View)

Order information

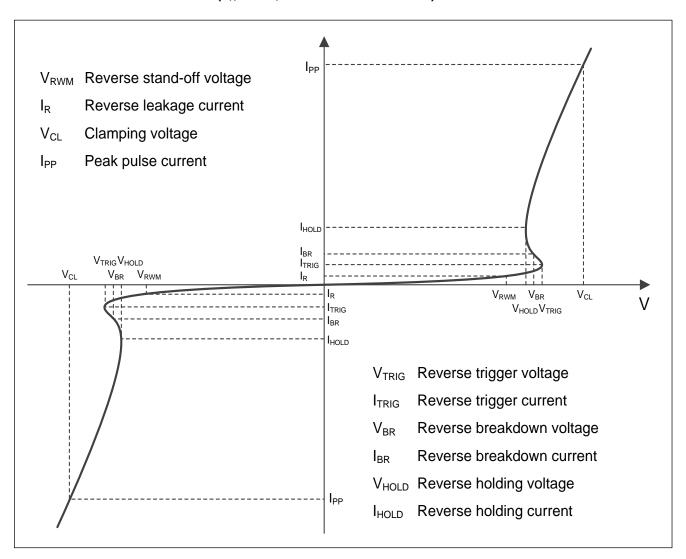
Device	Package	Shipping		
ESD9B5VL-2/TR	FBP-02C	10000/Tape&Reel		



Absolute maximum ratings

Parameter	Symbol	Rating	Unit	
Peak pulse power (t _p = 8/20µs)	P_{pk}	33	W	
Peak pulse current (t _p = 8/20µs)	I _{PP}	3	А	
ESD according to IEC61000-4-2 air discharge	V	±20	kV	
ESD according to IEC61000-4-2 contact discharge	V_{ESD}	±20		
Junction temperature	TJ	125	°C	
Operating temperature	T _{OP}	-40~85	°C	
Lead temperature	TL	260	°C	
Storage temperature	T _{STG}	-55~150	°C	

Electrical characteristics (T_A=25 °C, unless otherwise noted)



Definitions of electrical characteristics



Electrical characteristics (T_A=25 °C, unless otherwise noted)

Parameter	Symbol	Condition	Min.	Тур.	Max.	Unit
Reverse stand-off voltage	V_{RWM}				±5	V
Reverse leakage current	I _R	V _{RWM} = 5V		<1	100	nA
Reverse breakdown voltage	V_{BR}	I _{BR} = 1mA	5.8		8.3	V
Clamping voltage 1)	V _{CL}	$I_{PP} = 16A, t_p = 100ns$		13		V
Clamping voltage 2)	V _{CL}	V _{ESD} = 8kV		13		V
Clamping voltage 3)	V _{CL}	$I_{PP} = 1A, t_p = 8/20 \mu s$			8.5	V
Clamping voltage		$I_{PP} = 3A, t_p = 8/20 \mu s$			11	V
Dynamic resistance 1)	R _{DYN}			0.4		Ω
lunction conscitones	CJ	V _R = 0V, f = 1MHz		5.0	7	pF
Junction capacitance		V _R = 5V, f = 1MHz		3.6	5	pF

Notes:

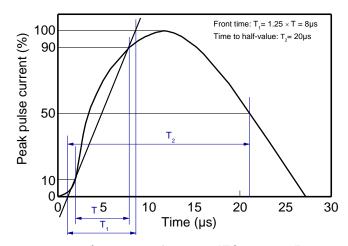
¹⁾ TLP parameter: $Z_0 = 50\Omega$, $t_p = 100$ ns, $t_r = 2$ ns, averaging window from 60ns to 80ns. R_{DYN} is calculated from 4A to 16A.

²⁾ Contact discharge mode, according to IEC61000-4-2.

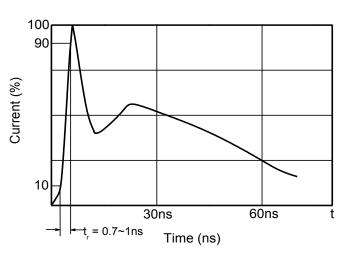
³⁾ Non-repetitive current pulse, according to IEC61000-4-5.



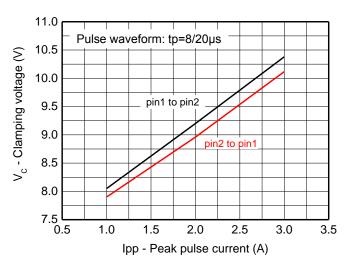
Typical characteristics (T_A=25°C, unless otherwise noted)



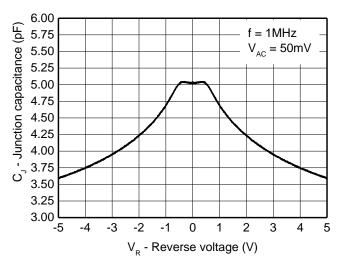
8/20µs waveform per IEC61000-4-5



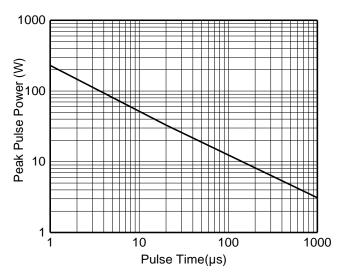
Contact discharge current waveform per IEC61000-4-2



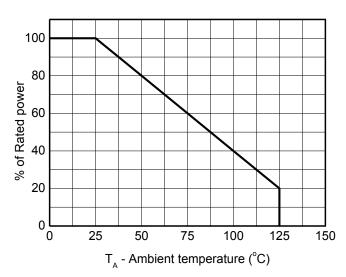
Clamping voltage vs. Peak pulse current



Capacitance vs. Reverse voltage



Non-repetitive peak pulse power vs. Pulse time

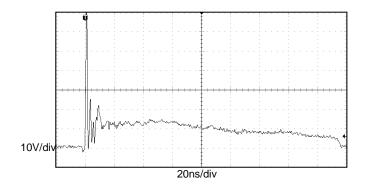


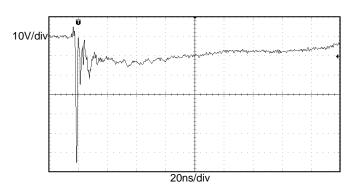
Power derating vs. Ambient temperature

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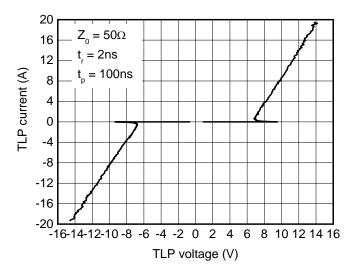
Typical characteristics (T_A=25°C, unless otherwise noted)





ESD clamping (+8kV contact discharge per IEC61000-4-2)

ESD clamping (-8kV contact discharge per IEC61000-4-2)

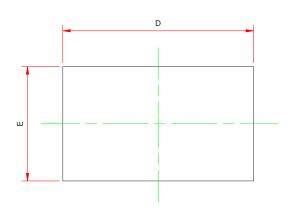


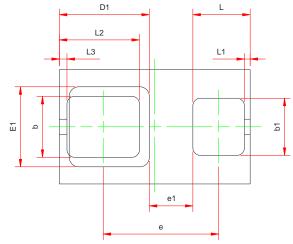
TLP Measurement



Package outline dimensions

FBP-02C

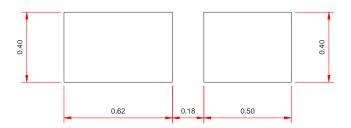




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	7			
∢	A1			

Symbol	Dimensions In Millimeters			
Symbol	Min.	Тур.	Max.	
А	0.450	0.500	0.550	
A1	0.010		0.100	
D	0.950	1.000	1.050	
Е	0.550	0.650		
D1	0.470 Ref.			
E1	0.420 Ref.			
b	0.270	0.320	0.370	
b1	0.250	0.300	0.350	
е	0.555	0.655		
e1	0.230 Ref.			
L	0.250	0.300	0.350	
L1	0.030 Ref.			
L2	0.370	0.420	0.470	
L3	0.040 Ref.			

Recommend land pattern (Unit: mm)



Notes:

This recommended land pattern is for reference purposes only. Please consult your manufacturing group to ensure your PCB design guidelines are met.